

# TECHNICAL REPORT



**Dynamic modules –  
Part 6-5: Investigation of operating mechanical shock and vibration tests for  
dynamic modules**

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## CONTENTS

FOREWORD.....	4
1 Scope.....	6
2 Background.....	6
3 Questionnaire results in Japan.....	6
4 Evaluation plan.....	7
5 Evaluation results.....	7
5.1 Step 1.....	7
5.1.1 Evaluation of hammer impact.....	7
5.1.2 Evaluation of adjacent board insertion and rack handle impact.....	9
5.2 Step 2.....	9
5.3 Step 3.....	11
5.3.1 MEMS-VOA.....	11
5.3.2 WSS and tunable laser.....	14
6 Simulation.....	16
6.1 Simulation model.....	16
6.2 Frequency characteristics.....	17
6.3 Dependence on board design.....	17
6.4 Consistency of evaluation and simulation results.....	18
7 Summary.....	19
8 Conclusions.....	19
Figure 1 – Photos of evaluating hammer impact, rack and boards.....	7
Figure 2 – Evaluation results of hammer impact H.....	8
Figure 3 – Photos of evaluating adjacent board insertion and rack handle impact.....	9
Figure 4 – DUT (VOA and WSS) installed on boards and rack for second step of the evaluation.....	10
Figure 5 – Oscilloscope display of waveform changes in vibration and optical output.....	10
Figure 6 – Evaluation results when employing MEMS-VOA for Z axis.....	11
Figure 7 – Photos of the MEMS-VOA shock/vibration test equipment.....	12
Figure 8 – Operational shock characteristics of MEMS-VOA.....	13
Figure 9 – Vibration evaluation results for MEMS-VOA (Z axis; 2 G).....	13
Figure 10 – Shock and vibration evaluation system for WSS and tunable laser.....	14
Figure 11 – Shock evaluation results for WSS (directional dependence).....	15
Figure 12 – Shock evaluation results for WSS (z-axis direction and shock dependence).....	15
Figure 13 – Simulation model.....	16
Figure 14 – Vibration simulation results (Conditions: 1,6 mm × 240 mm × 220 mm, t × H × D).....	17
Figure 15 – Vibration simulation results (Dependence on board conditions).....	18
Table 1 – Rack and board specifications, conditions of evaluating hammer impact and acquiring data.....	8
Table 2 – Dynamic modules used in evaluation and evaluation conditions.....	10
Table 3 – Conditions for MEMS-VOA vibration/shock evaluation.....	12
Table 4 – Results of MEMS-VOA vibration evaluation.....	14

Table 5 – Conditions for simulating board shock and vibration .....	16
Table 6 – Comparison of hammer impact shock evaluation results and vibration simulation (Conditions: 1,6 mm × 240 mm × 220 mm, t × H × D) .....	19

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**Part 6-5: Investigation of operating mechanical shock  
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